





# The 15th Electronic Circuits World Convention

第十五屆世界電子電路大會

30 Nov – 2 Dec Hong Kong / Shenzhen



# Paper Presentation

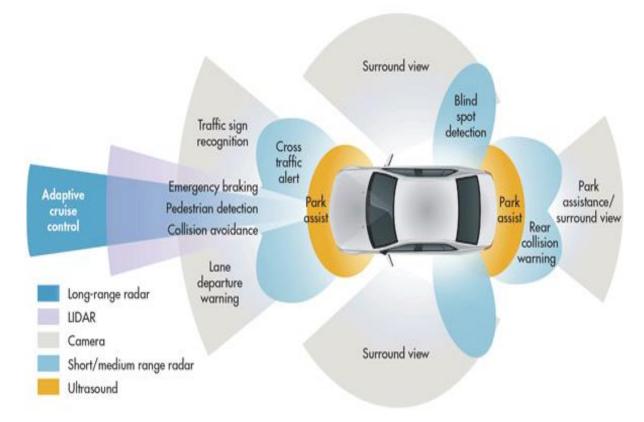
ELECTRICAL AND MECHANICAL RELIABILITY OF AN RF LAMINATE ARE KEY REQUIREMENTS FOR SELECTION IN 77/79 GHZ SAFETY AND RELIABILITY APPLICATIONS

MANFRED HUSCHKA, VICE PRESIDENT AGC MULTI-MATERIALS GENERAL DIVISION, RF BUSINESS UNIT



#### ADAS APPLICATIONS

Advanced driver-assistance systems (ADAS) are electronic systems that assist drivers in driving and parking functions









#### 77GHZ ADAS SENSOR



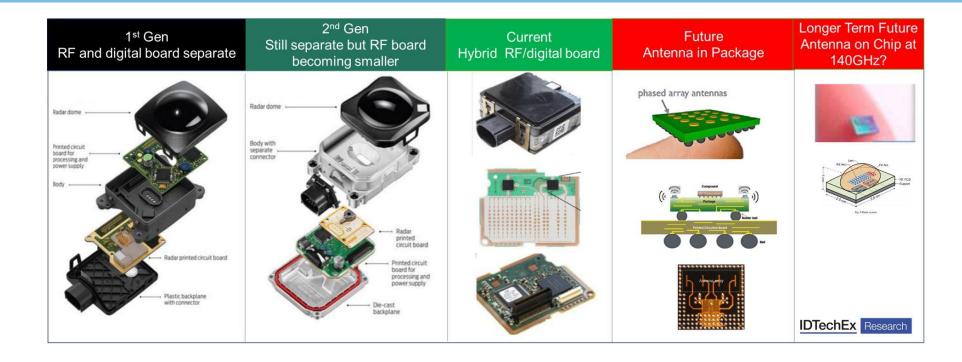






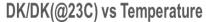


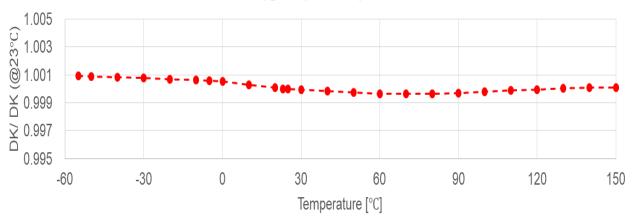
#### 77GHZ ADAS SENSOR



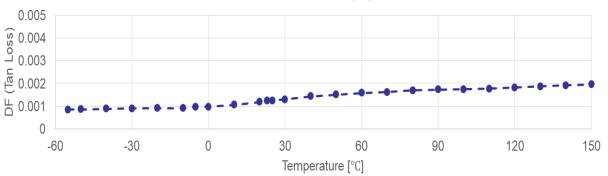


## STABLE DK/DK AND DF FROM -60 TO +150 °C





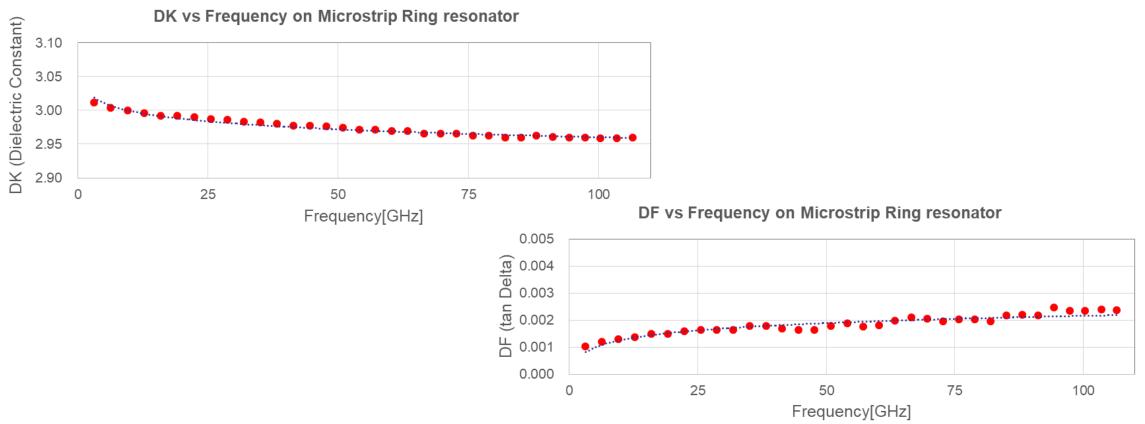
#### **DF** vs Temperature [°C]





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#### STABLE DK/DK AND DF UP TO 110 GHZ

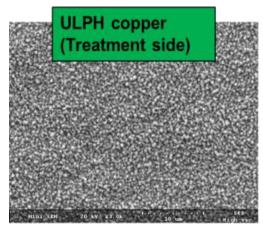


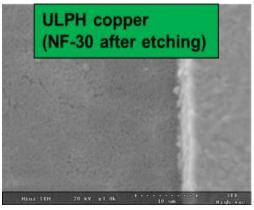


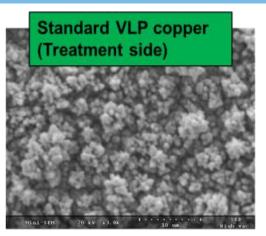


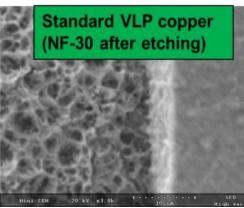
#### COPPER FOIL IS ALSO OF IMPORTANCE

ULPH copper foil vs. VLPH copper foil







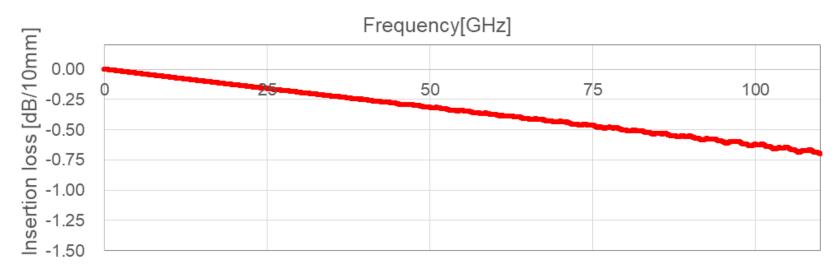






#### COPPER FOIL INFLUENCE ON INSERTION LOSS

#### **DK vs Frequency on MS Ring resonator**

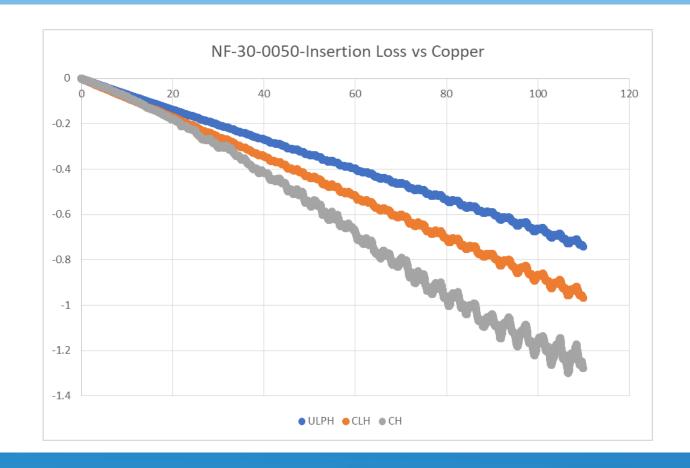








#### COPPER FOIL INFLUENCE ON INSERTION LOSS

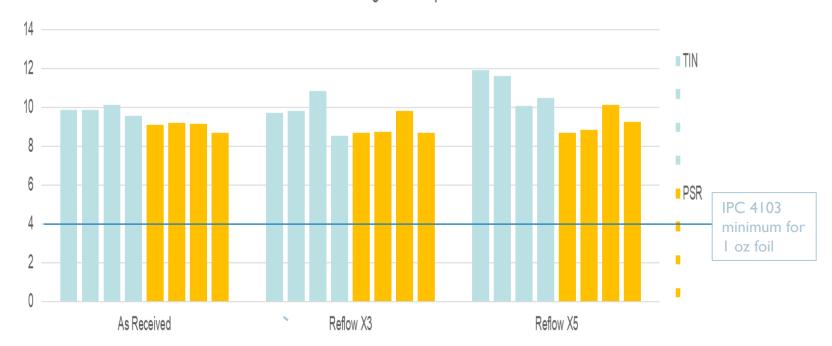






#### COPPER FOIL MECHANICAL RELIABILITY

#### Cu 0.5Oz. ULP Peel Strength vs Repeated Reflow





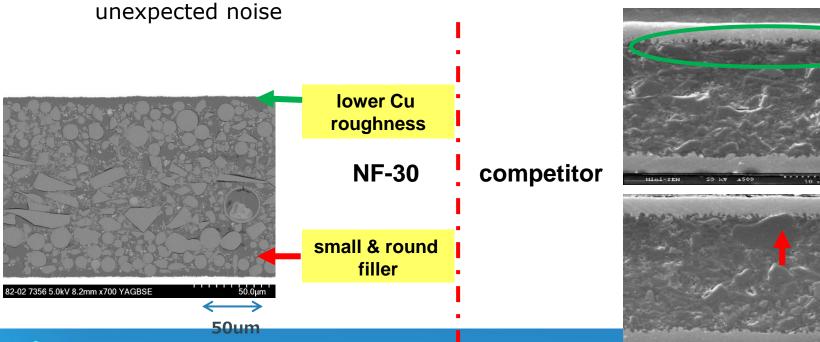


#### ADVANCED FILLER SYSTEM + ULP COPPER FOIL

#### NF-30 uses small and round shape filler systems

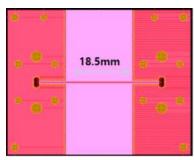
- ✓ Smoother interface between copper foil and dielectric layer
- ✓ Much less chance for fillers to touch the copper foil area.

✓ Larger box type fillers touching copper foil treatment side could raise



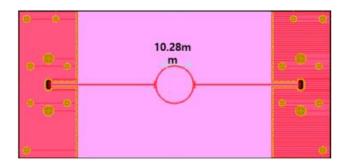


#### MICROSTRIP RING RESONATOR TEST COUPONS



- NF-30-0050 ULPH/ULPH
- Microstrip ring resonator test method
   using waveguide connector (WR-12)





Coupon for Insertion Loss (short: 18.5 mm, long: 53 mm)

Coupon for DK (ring diameter: 10.28 mm)



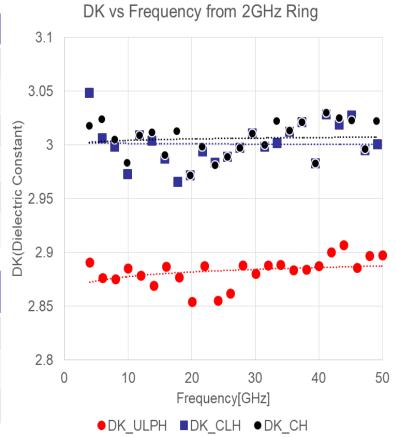




#### NF-30 DK IS INFLUENCED BY COPPER FOIL TYPE

NF-30-0050						
Freq.	DK ULPH	Freq.	DK CLH	Freq.	DK CH	
10.011	2.885	9.881	2.973	9.866	2.983	
20.118	2.854	19.765	2.972	19.765	2.972	
30.055	2.880	29.481	3.010	29.481	3.010	
40.032	2.887	39.465	2.983	39.465	2.983	
49.962	2.897	49.204	3.001	49.051	3.022	

Product	Expected Frequency Shift near 77GHz [GHz]		
NF-30-0050-CH	0.460	0.000	
NF-30-0050-CLH	0.696	0.236	
NF-30-0050-ULPH	1.863	1.403	



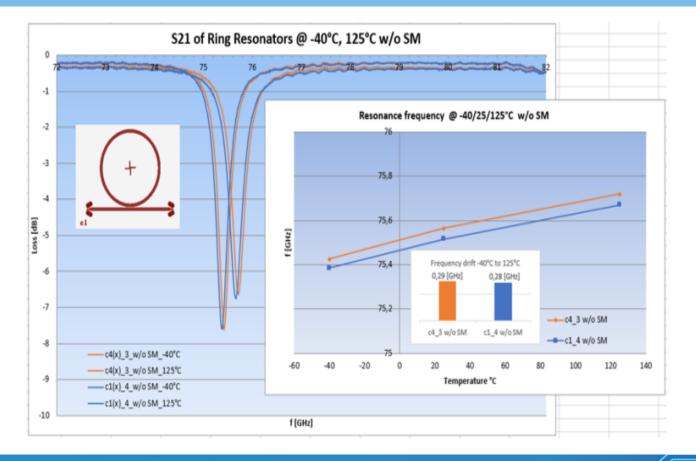






#### NF-30 ELECTRICAL STABILITY

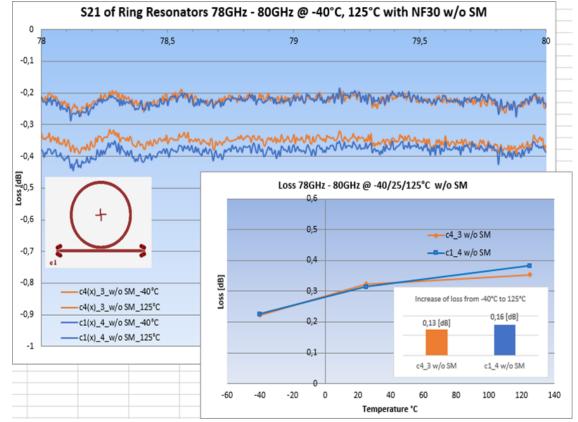
S21 of ring resonators show a quite small frequency drift





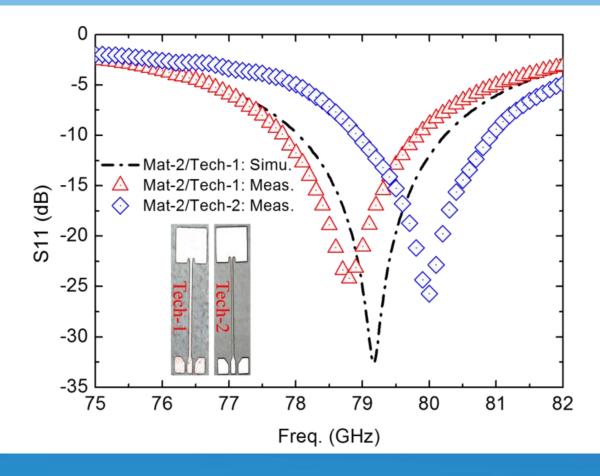
#### NF-30 ELECTRICAL STABILITY

S21 of ring resonators show an acceptable increase





#### INFLUENCE OF PCBTECHNOLOGY ON SII





#### NF-30 THERMAL RELIABILITY

NF-30: 288 °C solder float

before



during





after 30 minutes!!



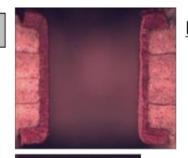


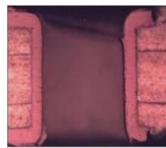


#### NF-30 EASY CONVERSION TO PCBS

Plated vias in 20 and 60 mil NF-30 viewed from x and y direction

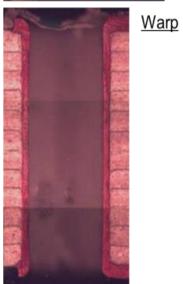
NF-30 20mil





NF-30 60mil





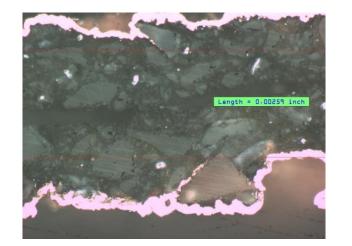






#### NF-30 HIGH CHEMICAL RESISTANCE



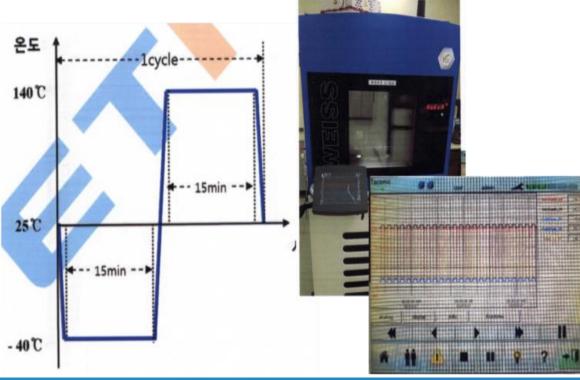






#### NF-30 THERMAL RELIABILITY IN MULTILAYER PCB

√ Thermal Cycling test condition
[ 1000 cycles: -40°C (15min) → (≤10sec) → 140°C (15min) ]

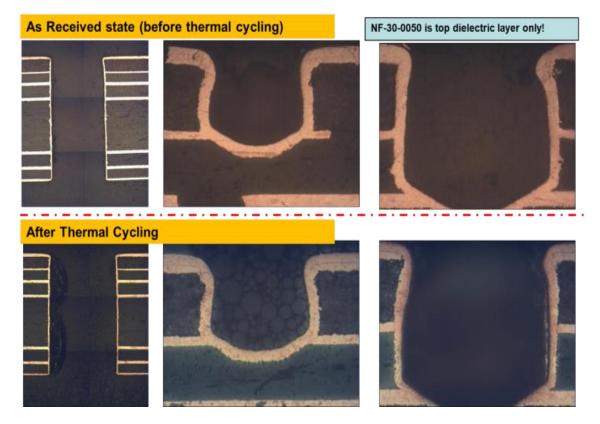






#### NF-30 THERMAL RELIABILITY IN MULTILAYER PCB

NF-30 hybrid multilayer before and after thermal cycling 1,000 cycles from -40°C to + 140°C



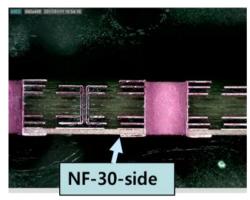


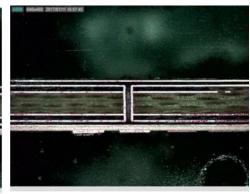




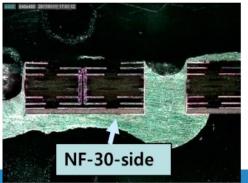
#### NF-30 THERMAL RELIABILITY IN MULTILAYER PCB

NF-30 hybrid multilayer after 50x solder float (10 s at 288 °C)





#### Solder Float (@288°C) 10s 50x









#### NF-30 – THE IDEAL PCB LAMINATE FOR ADAS

- Truly a high reliability RF base material
- Suitable for 77/79 GHz ADAS hybrid multilayer
- The combination of non-reinforced PTFE laminates with Almost No Profile copper foil is the ideal solution
- Provides the supply chain with a safe knowledge of long-term reliability in operation

NF-30 is already in mass production of several 77 GHz ADAS sensors

– evidence of all the above said





### YOU CAN CONTACT ME AT ANY TIME



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